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Facsimile Transmittal

To:	Fax Number	Voice Number
Examiner Monica Lewis (GAU 2822)	1-571-273-8300	

From: Marcus J. Millet

Date: February 21, 2006

No. Pages: 8

Original Mailed: No

Client/Matter No: TESSERA 3.0-139 DIV (TESSER.790)

• MESSAGE:

In accordance with your telephone call February 21, 2006, attached are copies of the following in connection with Patent Application Serial No. 09/854,269:

1. Post card stamped "received" 1/6/06 (1 page); and
2. Amendment Under 37 C.F.R. § 1.116 (6 pages).

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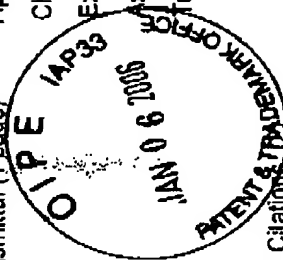
Atty Docket No.: TESSERA 3.0-139 DIV CONT Due Date: 1/6/05

Title: MICROELECTRONIC PACKAGES WITH SOLDER INTERCONNECTIONS

Application No.: Not Yet Assigned

Documents Filed:

Utility Patent Application Transmittal (1 page) Application Data Sheet (2 pages)
Fee Transmittal (1 page) Charge \$3,160 to deposit account 12-1095
Specification (27 pages) Extension Petition in parent S/N 09/854,269 (1 pg)
Format drawings (4 sheets) Amendment in parent S/N 09/854,269 (6 pgs)
IDS Cover (2 pages) Transmittal in parent S/N 09/854,269 (1 pg)
Form PTO-1449 (2 pages)
Copies of non-US Patent IDS Citations

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EXPEDITED PROCEDURE

Group Art Unit: 2822

Docket No.: TESSERA 3.0-139 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Thomas H. DiStefano

Application No.: 09/854,269

Filed: May 11, 2001

For: MICROELECTRONIC PACKAGES WITH
SOLDER INTERCONNECTIONS

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: Group Art Unit: 2822
:
: Examiner: M. Lewis
:
:
:**AMENDMENT UNDER 37 C.F.R. § 1.116**

MS AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Official Action dated December 2, 2004, finally rejecting claims 1-3, please amend the above-identified U.S. patent application as follows: